Cohu®

Eclipse™

One Platform, Scalable for Mobile, Automotive and AI Datacenter Test

Supports Low to Ultra-High-Power Applications Providing Unparalleled Flexibility and Efficiency

- **Multi-Market Versatility:** one platform supporting mobile to HPC devices simplifies factory operation and standardize test infrastructure across multiple product lines.
- **Scalable by Design:** a single handler architecture that scales in power, force, thermal capability, parallelism - supporting today's requirements and tomorrow's AI workloads without replacing the platform.
- **Configuration Flexibility:** modular configurations allow customers to deploy Eclipse for current needs and field-upgrade as device complexity increases - protecting capital investments.
- **Advanced Thermal Control:** T-Core™ Active Thermal Control maintains tight temperature control and fast responses, critical for achieving yield and performance accuracy in AI and high-power compute testing.
- **Industry 4.0:** AGV, OHT compatible Tray I/O.
- **AI Datacenter Ready:** designed to support high-power, high-density compute devices, including advanced processors used in AI training and inference datacenters.

Eclipse™

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T-Core™ THERMAL SYSTEM

Future-Proof Configurations - One Platform Mobile --> HPC

- Up to 12,000 UPH
- Parallelism x1 to x16
- Output bins: 3 auto, 3 manual
- Passive SLK and device kit compatible with competitors'
- Ultra-fast T-Core Active Thermal Control
- Same ATC in NPI and production
- NIST traceable thermal calibration
- Tight guard band for Start of Test (with load board/socket thermal conditioning option)
- Chamberless tri-temp, no LN2
- Field-upgradeable to ambient/hot ATC or tri-temp ATC (for passive configuration)
- Vision 2DiD/u2DiD device traceability
- Multiple Feedback Control modes available: HTF, DTF, PF, DTF-PF

Purchase Liquid-Cooled-Ready Passive & Quickly Swap Socket Layout Kit to Convert to Tri-Temp Active Thermal Control

Eclipse™

Mobile, Automotive, Industrial, Compute

- Packages: 3 x 3 mm to 110 x 110 mm
- Test force site: up to 650 kgf
- Power dissipation: upgradeable to 6kW T-Core X Active Thermal Control
- Parallelism: X1 to X16
- Passive to Tri-Temp: -40°C to +130°C

T-Core™ THERMAL SYSTEM

EclipseX™

Automotive, Compute, AI Datacenter

- Packages: 25 x 25 mm to 135 x 315 mm (full JEDEC tray size)
- Test force site: up to 900 kgf
- Power dissipation: 6kW T-Core X Active Thermal Control
- Parallelism: X1 to X8
- Tri-Temp only: -40°C to +130°C
- Multiple high-capacity chiller options available

ll specifications are subject to change without notification and are for reference only. For detailed performance specifications, please contact Cohu.

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